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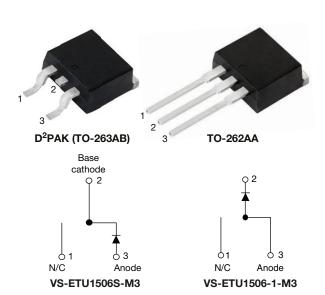




www.vishay.com

Vishay Semiconductors

Ultra Fast Rectifier, 15 A FRED Pt®



PRIMARY CHARACTERISTICS						
I _{F(AV)}	15 A					
V_{R}	600 V					
V _F at I _F	1.1 V					
t _{rr} (typ.)	24 ns					
T_J max.	175 °C					
Package	D ² PAK (TO-263AB), TO-262AA					
Circuit configuration	Single					

FEATURES

- Low forward voltage drop
- · Ultrafast recovery time
- 175 °C operating junction temperature
- Low leakage current



- Designed and qualified according to JEDEC®-JESD 47
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION

State of the art, ultralow V_F, soft-switching ultrafast rectifiers optimized for discontinuous (critical) mode (DCM) power factor correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units, and DVD AC/DC power supplies.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Repetitive peak reverse voltage	V_{RRM}		600	V			
Average rectified forward current	I _{F(AV)}	T _C = 143 °C	15	۸			
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	160	A			
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-	.,	
Forward voltage	V _F	I _F = 15 A	-	1.35	1.9	V	
		I _F = 15 A, T _J = 150 °C	-	1.1	1.3		
Reverse leakage current		$V_R = V_R$ rated	-	0.01	15		
neverse leakage current	I _R	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{ rated}$	-	20	200	μA	
Junction capacitance	C _T	V _R = 600 V	-	12	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH	



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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
		$I_F = 1 A, dI_F/dt = 1$	00 A/μs, V _R = 30 V	1	24	28		
Reverse recovery time		$I_F = 15 \text{ A}, dI_F/dt =$	100 A/ μ s, $V_R = 30 V$	-	36	47	ns	
neverse recovery time	t _{rr}	T _J = 25 °C		-	40	-	115	
		T _J = 125 °C	$I_F = 15 \text{ A}$ $dI_F/dt = 200 \text{ A/µs}$ $V_B = 390 \text{ V}$	1	87	-		
Peak recovery current	I _{RRM}	T _J = 25 °C		-	5	-	Α	
Feak recovery current		T _J = 125 °C		-	9.0	-	^	
Reverse recovery charge	0	T _J = 25 °C	VR = 390 V	-	107	-	С	
heverse recovery charge	Q _{rr}	T _J = 125 °C		-	430	-		
Reverse recovery time	t _{rr}		I _F = 15 A	-	53	-	ns	
Peak recovery current	I _{RRM}	T _J = 125 °C	$dI_F/dt = 800 A/\mu s$	-	25	-	Α	
Reverse recovery charge	Q _{rr}		V _R = 390 V	=	730	-	nC	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C	
Thermal resistance, junction-to-case	R _{thJC}	R _{thJC}		1.3	1.51	°C/W	
Thermal resistance, junction-to-ambient	R _{thJA}	R _{thJA} Typical socket mount		-	70		
Thermal resistance, case-to-heat sink	R _{thCS}	R _{thCS} Mounting surface, flat, smooth, and greased		0.5	-		
Weight			-	2.0	-	g	
weight			-	0.07	-	OZ.	
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)	
Marking daving		Case style D ² PAK (TO-263AB)		ETU.	506S	•	
Marking device		Case style TO-262	ETU1506-1				

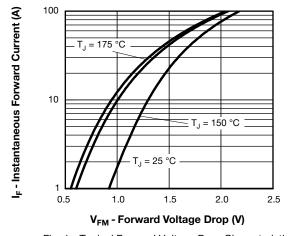


Fig. 1 - Typical Forward Voltage Drop Characteristics

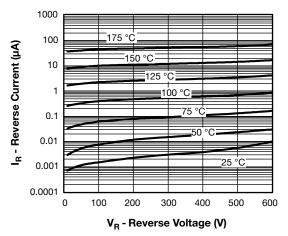


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

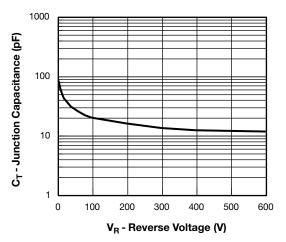


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

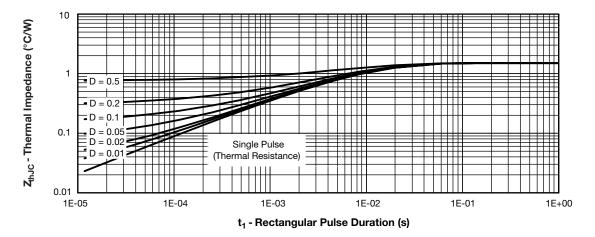


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

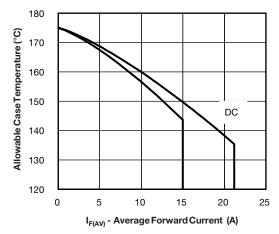


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

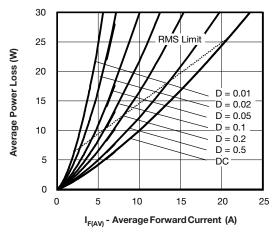


Fig. 6 - Forward Power Loss Characteristics

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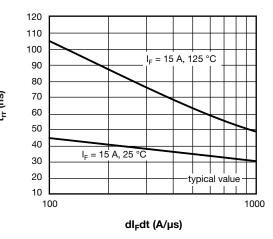
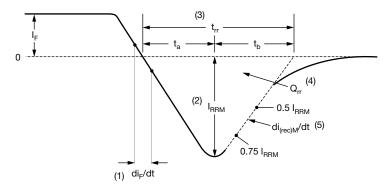


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

900 800 700 I_F = 15 A, 125 °C 600 Q_{rr} (nC) 500 400 300 I_F = 15 A, 25 °C 200 10 typical value 0 100 1000 dl_Fdt (A/μs)

Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) $\rm I_{RRM}$ peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

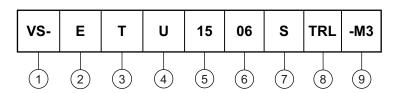
(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

Circuit configuration
E = single diode

3 - T = TO-220

U = ultrafast recovery time

- Current code (15 = 15 A)

6 - Voltage code (06 = 600 V)

- • S = D^2PAK (TO-263AB)

- • -1 = TO-262AA

• None = tube (50 pieces)

- • TRL = tape and reel (left oriented, for D²PAK (TO-263AB) package)

- • TRR = tape and reel (right oriented, for D²PAK (TO-263AB) package)

9 - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-ETU1506S-M3	50	1000	Antistatic plastic tube				
VS-ETU1506-1-M3	50	1000	Antistatic plastic tube				
VS-ETU1506STRR-M3	800	800	13" diameter reel				
VS-ETU1506STRL-M3	800	800	13" diameter reel				

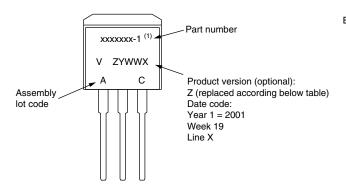
LINKS TO RELATED DOCUMENTS						
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?96164				
Differsions	TO-262AA	www.vishay.com/doc?96165				
Part marking information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444				
Part marking information	TO-262AA	www.vishay.com/doc?95443				
Packaging information	D ² PAK (TO-263AB)	www.vishay.com/doc?96424				
SPICE model		www.vishay.com/doc?96132				



Part Marking Information

Vishay Semiconductors

TO-262



Example: This is a xxxxxxx-1 (1) with assembly lot code AC, assembled on WW 19, 2001

in the assembly line "X"

Note

(1) If part number contain "H" as last digit, product is AEC-Q101 qualified

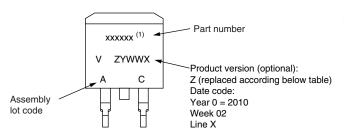
ENVIRONMENTAL NAMING CODE (Z)	PRODUCT DEFINITION			
A	Termination lead (Pb)-free			
В	Totally lead (Pb)-free			
E	RoHS-compliant and termination lead (Pb)-free			
F	RoHS-compliant and totally lead (Pb)-free			
М	Halogen-free, RoHS-compliant and termination lead (Pb)-free			
N	Halogen-free, RoHS-compliant and totally lead (Pb)-free			
G	Green			



Part Marking Information

Vishay Semiconductors

D²PAK



Example: This is a xxxxxx ⁽¹⁾ with assembly lot code AC, assembled on WW 02, 2010

Note

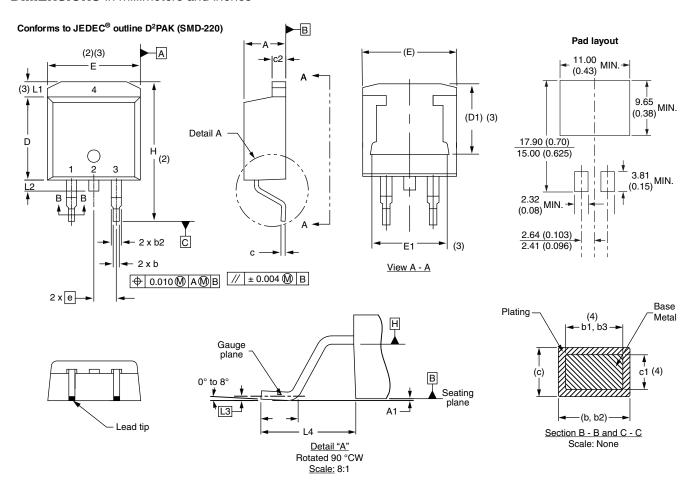
(1) If part number contain "H" as last digit, product is AEC-Q101 qualified

ENVIRONMENTAL NAMING CODE (Z)	PRODUCT DEFINITION			
А	Termination lead (Pb)-free			
В	Totally lead (Pb)-free			
E	RoHS-compliant and termination lead (Pb)-free			
F	RoHS-compliant and totally lead (Pb)-free			
M	Halogen-free, RoHS-compliant, and termination lead (Pb)-free			
N	Halogen-free, RoHS-compliant, and totally lead (Pb)-free			
G Green				



D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INC	HES	NOTES	SYMBOL	MILLIM	ETERS	INC	HES	NOTES	
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES		STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4 e 2.54 BSC 0.100 BSC		2.54 BSC		BSC			
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

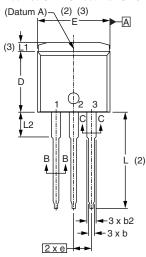
Revision: 13-Jul-17 Document Number: 96164

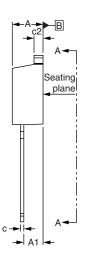


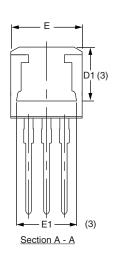
TO-262AA

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262







⊕ 0.010 **M** A**M** B

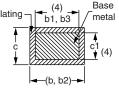
Lead assignments



Diodes

1. - Anode (two die)/open (one die) 2., 4. - Cathode

3. - Anode



Section B - B and C - C Scale: None

SYMBOL	MILLIN	IETERS	INC	INCHES			
OTHIDOL	MIN.	MAX.	MIN.	MAX.	NOTES		
Α	4.06	4.83	0.160	0.190			
A1	2.03	3.02	0.080	0.119			
b	0.51	0.99	0.020	0.039			
b1	0.51	0.89	0.020	0.035	4		
b2	1.14	1.78	0.045	0.070			
b3	1.14	1.73	0.045	0.068	4		
С	0.38	0.74	0.015	0.029			
c1	0.38	0.58	0.015	0.023	4		
c2	1.14	1.65	0.045	0.065			
D	8.51	9.65	0.335	0.380	2		
D1	6.86	8.00	0.270	0.315	3		
Е	9.65	10.67	0.380	0.420	2, 3		
E1	7.90	8.80	0.311	0.346	3		
е	2.54	BSC	0.100	BSC			
L	13.46	14.10	0.530	0.555			
L1	-	1.65	-	0.065	3		
L2	3.56	3.71	0.140	0.146			

Notes

(4) Dimension b1 and c1 apply to base metal only

Controlling dimension: inches

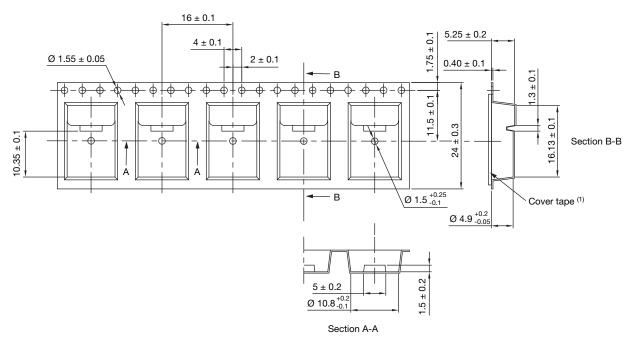
⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994
(2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

Thermal pad contour optional within dimension E, L1, D1 and E1

Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)

D²PAK (TO-263AB)

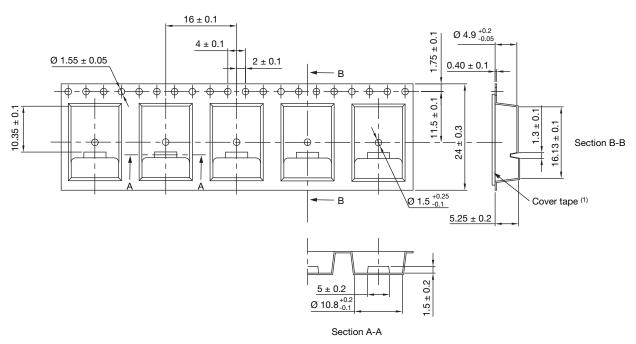
CARRIER TAPE FOR TAPE AND REEL LEFT in millimeters



Note

(1) For dimensions, see next pages

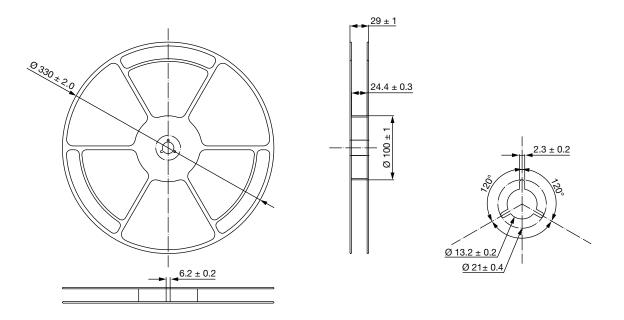
CARRIER TAPE FOR TAPE AND REEL RIGHT in millimeters



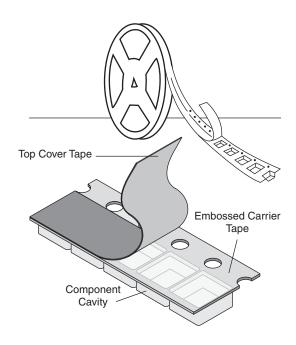
Note

(1) For dimensions, see next pages

REEL FOR CARRIER TAPE in millimeters



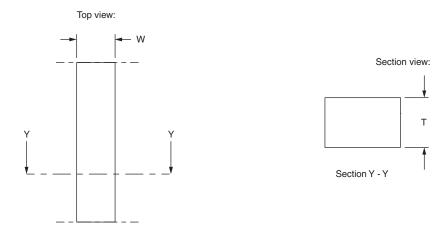
CARRIER TAPE AND REEL PACKAGING D²PAK (TO-263AB)



Packaging Information

Vishay Semiconductors

COVER TAPE FOR CARRIER TAPE in millimeters



APPLICATION	COVER TAPE WIDTH W	COVER TAPE THICKNESS T	CARRIER TAPE WIDTH	MATERIAL
D ² PAK (TO-263AB)	21.3 ± 0.1	0.060 ± 0.01	24	Antistatic/treated/transparent/polyester



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Vishay

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